

N-channel vertical D-MOS transistor**2N7002****FEATURES**

- Direct interface to C-MOS, TTL, etc.
- High-speed switching
- No secondary breakdown.

DESCRIPTION

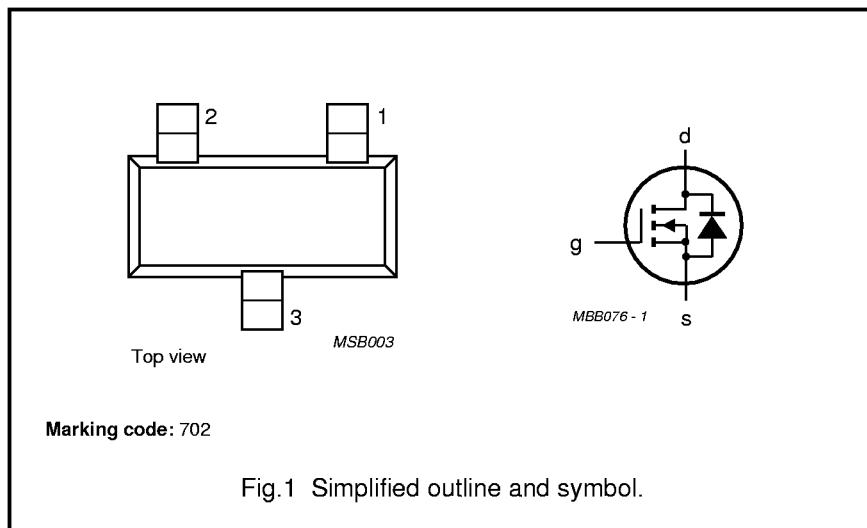
N-channel enhancement mode vertical D-MOS transistor in a SOT23 envelope. It is designed for use as a Surface Mounted Device (SMD) in thin and thick-film circuits, with applications in relay, high-speed and line transformer drivers.

PINNING - SOT23

PIN	DESCRIPTION
1	gate
2	source
3	drain

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MAX.	UNIT
V_{DS}	drain-source voltage		60	V
I_D	drain current	DC value	180	mA
$R_{DS(on)}$	drain-source on-resistance	$I_D = 500 \text{ mA}$ $V_{GS} = 10 \text{ V}$	5	Ω
$V_{GS(th)}$	gate-source threshold voltage	$I_D = 1 \text{ mA}$ $V_{GS} = V_{DS}$	3	V

PIN CONFIGURATION

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2N7002

LIMITING VALUES

In accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{DS}	drain-source voltage		–	60	V
$\pm V_{GSO}$	gate-source voltage	open drain	–	40	V
I_D	drain current	DC value	–	180	mA
I_{DM}	drain current	peak value	–	800	mA
P_{tot}	total power dissipation	$T_{amb} = 25 \text{ }^{\circ}\text{C}$ (note 1) (note 2)	–	300	mW
T_{stg}	storage temperature range		–65	150	$^{\circ}\text{C}$
T_j	junction temperature		–	150	$^{\circ}\text{C}$

Notes

1. Mounted on a ceramic substrate measuring $10 \times 8 \times 0.7$ mm.
2. Mounted on a printed circuit board.

THERMAL RESISTANCE

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j-a}$	from junction to ambient	note 1 note 2	430 500	K/W K/W

Notes

1. Mounted on a ceramic substrate measuring $10 \times 8 \times 0.7$ mm.
2. Mounted on a printed circuit board.

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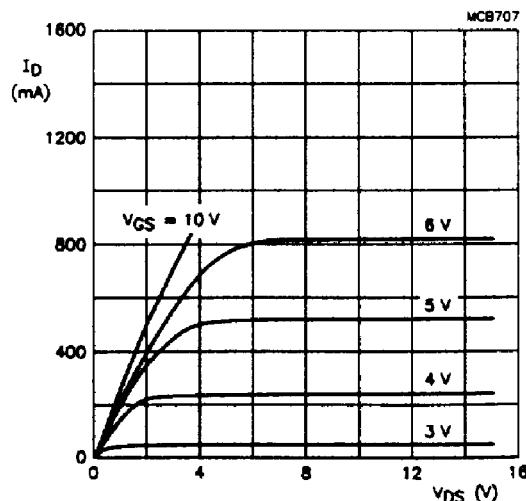
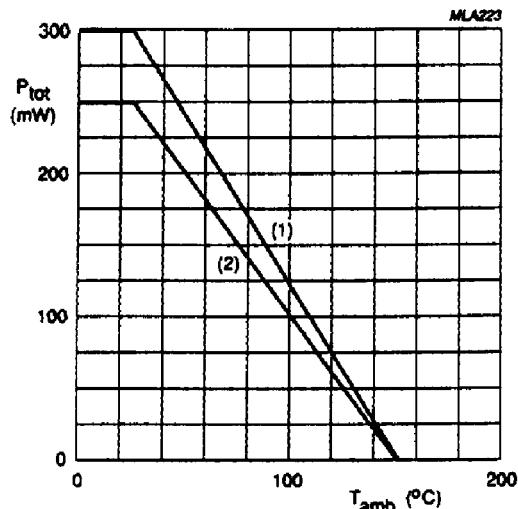
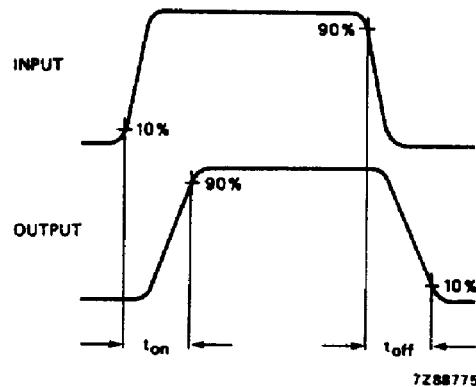
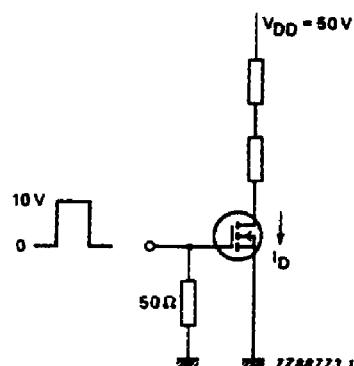
2N7002

CHARACTERISTICS $T_j = 25^\circ\text{C}$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_{(\text{BR})\text{DSS}}$	drain-source breakdown voltage	$I_D = 10 \mu\text{A}$ $V_{GS} = 0$	60	90	—	V
I_{DSS}	drain-source leakage current	$V_{DS} = 48 \text{ V}$ $V_{GS} = 0$	—	—	1	μA
$\pm I_{\text{GSS}}$	gate-source leakage current	$V_{DS} = 0$ $\pm V_{GS} = 15 \text{ V}$	—	—	10	nA
$V_{GS(\text{th})}$	gate-source threshold voltage	$I_D = 1 \text{ mA}$ $V_{GS} = V_{DS}$	0.8	—	3	V
$R_{DS(\text{on})}$	drain-source on-resistance	$I_D = 500 \text{ mA}$ $V_{GS} = 10 \text{ V}$	—	3.5	5	Ω
		$I_D = 75 \text{ mA}$ $V_{GS} = 4.5 \text{ V}$	—	—	5.3	Ω
$ Y_{fs} $	transfer admittance	$I_D = 200 \text{ mA}$ $V_{DS} = 10 \text{ V}$	100	200	—	mS
C_{iss}	input capacitance	$V_{DS} = 10 \text{ V}$ $V_{GS} = 0$ $f = 1 \text{ MHz}$	—	25	40	pF
C_{oss}	output capacitance	$V_{DS} = 10 \text{ V}$ $V_{GS} = 0$ $f = 1 \text{ MHz}$	—	22	30	pF
C_{rss}	feedback capacitance	$V_{DS} = 10 \text{ V}$ $V_{GS} = 0$ $f = 1 \text{ MHz}$	—	6	10	pF
Switching times (see Figs 2 and 3)						
t_{on}	turn-on time	$I_D = 200 \text{ mA}$ $V_{DD} = 50 \text{ V}$ $V_{GS} = 0 \text{ to } 10 \text{ V}$	—	—	10	ns
t_{off}	turn-off time	$I_D = 200 \text{ mA}$ $V_{DD} = 50 \text{ V}$ $V_{GS} = 0 \text{ to } 10 \text{ V}$	—	—	15	ns

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2N7002



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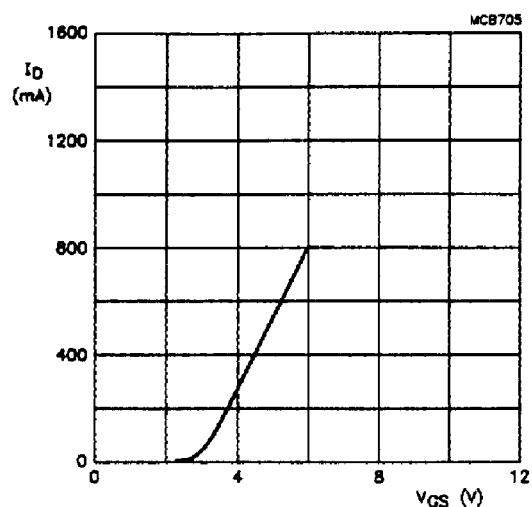


Fig.6 Typical transfer characteristic; $V_{DS} = 10$ V;
 $T_j = 25$ °C.

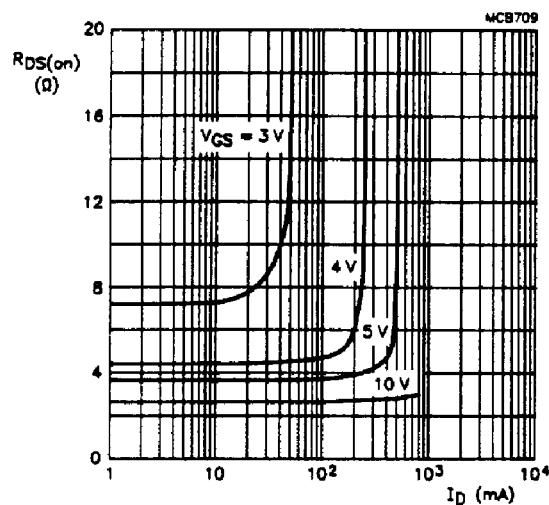


Fig.7 Typical on-resistance as a function of drain current; $T_j = 25$ °C.

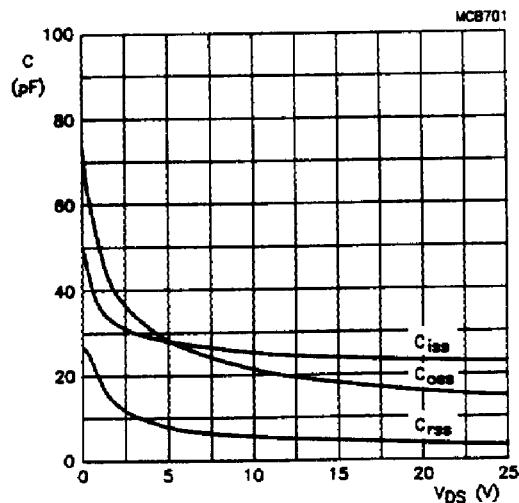


Fig.8 Typical capacitances as a function of drain-source voltage; $V_{GS} = 0$; $f = 1$ MHz;
 $T_j = 25$ °C.

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2N7002

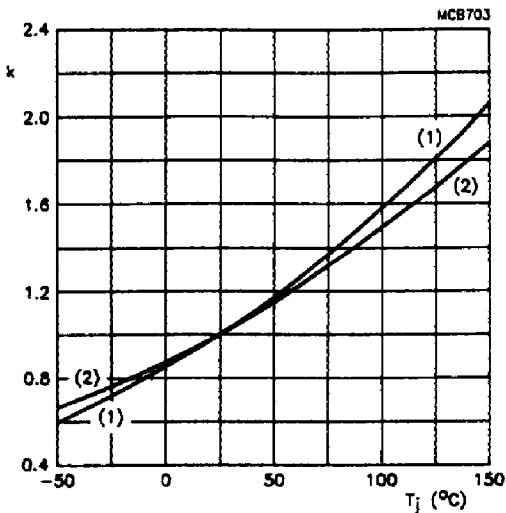
(1) I_D = 500 mA; V_{GS} = 10 V.(2) I_D = 75 mA; V_{GS} = 4.5 V.

Fig.9 Temperature coefficient of drain-source on-resistance;

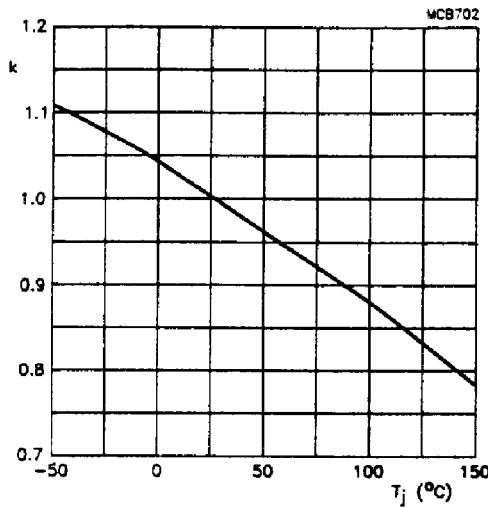


Fig.10 Temperature coefficient of gate-source threshold voltage;

$$k = \frac{V_{GS(th)} \text{ at } T_j}{V_{GS(th)} \text{ at } 25^\circ\text{C}}$$

typical V_{GS(th)} at 1 mA.

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2N7002

PACKAGE OUTLINE

Plastic surface mounted package; 3 leads

SOT23

